

General-Purpose 4ch Electronic Volume with Built-in Advanced Switch **BD3464FV**

General Description

BD3464FV is a 4ch electronic volume which has the best audio efficiency in the industry. It has a volume switching shock sound prevention technique called "Advanced Switch," supporting the construction of high quality car audio space by simple control.

Features

- Reduce switching noise of volume by using Advanced Switch circuit.
- Energy-saving design resulting in low-current consumption by utilizing the Bi-CMOS process. It has the advantage in quality over scaling down the power heat control of the internal regulators.
- Arranges all I/O terminals together for easier PCB layout and smaller PCB area.
- I²C BUS can be controlled by 3.3V / 5V.

Applications

It is optimal for car audio. It can also be used for car navigation, audio equipment of mini Compo, micro Compo, DVD, TV, etc.

Key Specifications

- Power Supply Voltage Range:
- Circuit Current (no signal):
- Total Harmonic Distortion:
- Maximum Input Voltage:
- Cross-talk between Selectors:
- Volume Control Range:
- Output Noise Voltage:
- Residual Output Noise Voltage:
- Operating Temperature Range:
 - -40°C to +85°C

Package

W(Typ) x D(Typ) x H(Max)

7.0V to 9.5V 25mA (Typ)

0.0004%(Typ)

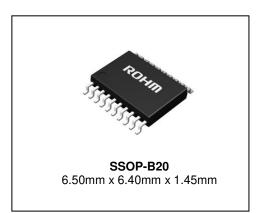
2.35Vrms (Typ)

+23dB to -79dB

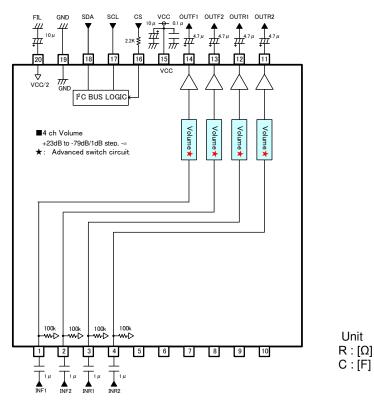
1.9µVrms(Typ)

1.6µVrms (Typ)

-105dB (Typ)

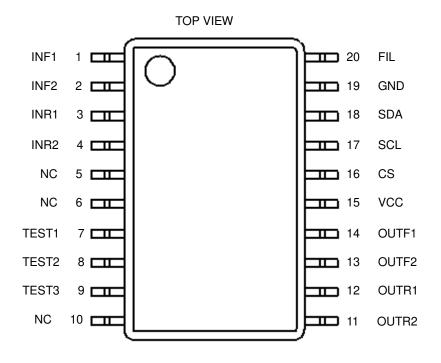


Typical Application Circuit



OProduct structure : Silicon monolithic integrated circuit OThis product has no designed protection against radioactive rays

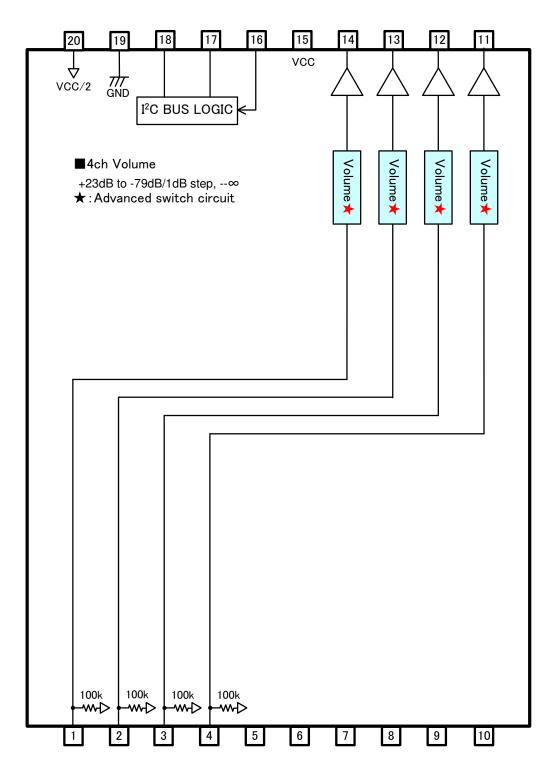
Pin Configuration



Pin Descriptions

Pin No.	Pin Name	Description	Pin No.	Pin Name	Description
1	INF1	1ch Front input terminal	11	OUTR2	2ch Rear output terminal
2	INF2	2ch Front input terminal	12	OUTR1	1ch Rear output terminal
3	INR1	1ch Rear input terminal	13	OUTF2	2ch Front output terminal
4	INR2	2ch Rear input terminal	14	OUTF1	1ch Front output terminal
5	NC		15	VCC	Power supply terminal
6	NC		16	CS	Chip select terminal
7	TEST1	Test Pin	17	SCL	I ² C Communication clock terminal
8	TEST2	Test Pin	18	SDA	I ² C Communication data terminal
9	TEST3	Test Pin	19	GND	GND terminal
10	NC		20	FIL	VCC/2 terminal

Block Diagram



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Power Supply Voltage	Vcc	10.0V	V
Input Voltage	V _{IN}	V _{CC} +0.3 to GND-0.3	V
Power Dissipation	Pd	0.81 (Note 1)	W
Storage Temperature	Tastg	-55 to +150	°C

(Note 1) This value decreases 6.5mW/°C for Ta=25°C or more when mounted on ROHM standard board. Thermal resistance θja=153.8 (°C/W) ROHM Standard board Size : 70 x 70 x 1.6(mm³)

Material : FR4 grass epoxy board(3% or less of copper foil area)

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Recommended Operating Conditions

Parameter	Symbol			Unit		
Farameter	Symbol	Min	Тур Мах		Unit	
Power Supply Voltage	Vcc	7.0	-	9.5	V	
Temperature	Topr	-40	-	+85	°C	

Electrical Characteristics

(Unless specified, Ta=25°C, V_{CC}=8.5V, f=1kHz, V_{IN}=1Vrms, Rg=600Ω, R_L=10kΩ, INF1 input, Volume 0dB)

CK	Demonstern	Symbol		Limit		11	Conditions	
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions	
	Circuit Current (No Signal)	la	-	25	40	mA	No signal	
	Voltage Gain	Gv	-1.5	0	+1.5	dB	$G_V=20log(V_{OUT}/V_{IN})$	
	Channel Balance	СВ	-1.5	0	+1.5	dB	CB=G _{V1} -G _{V2}	
	Total Harmonic Distortion	THD	-	0.0004	0.05	%	V _{OUT} =1Vrms BW=400Hz-30KHz	
GENERAL	Output Noise Voltage *	V _{NO}	-	1.9	10	μVrms	Rg=0Ω BW=IHF-A	
	Residual Output Noise Voltage *	V _{NOR}	-	1.6	10	μVrms	Volume=-∞dB Rg=0Ω BW=IHF-A	
	Cross-talk Between Channels *	CTC	-	-105	-90	dB	Rg=0Ω CTC=20log(V _{OUT} /V _{IN}) BW=IHF-A	
	Ripple Rejection	RR	-	-80	-40	THD	f=100Hz V _{RR} =100mVrms RR=20log(V _{OUT} /V _{CC} IN)	

Electrical Characteristics – continued

(Unless specified, Ta=25°C, V_{CC}=8.5V, f=1kHz, V_{IN}=1Vrms, Rg=600Ω, R_L=10kΩ, INF1 input, Volume 0dB)

	_			Limit	·		
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
	Input Impedance	RIN_V	70	100	130	kΩ	
	Maximum Input Voltage	VIM	2	2.35	-	Vrms	V _{IM} AT THD+N(V _{OUT})=1% BW=400Hz-30KHz
	Maximum Gain	Gv_bst	21	23	25	dB	$\begin{array}{l} GAIN=23DB \\ V_{IN}=100mVrms \\ G_V=20log(V_{OUT}/V_{IN}) \end{array}$
VOLUME	Maximum Attenuation *	Gv_min	-	-109	-90	dB	Volume=-∞dB G _V =20log(V _{OUT} /V _{IN}) BW=IHF-A
, OLI	Step Resolution	GV_STEP	-	1	-	dB	GAIN&ATT=+23dB to -79dB
>	Gain Set Error	Gv_err	-2	0	+2	dB	GAIN=+1dB to +23dB
	Attenuation Set Error 1	Gv_err1	-2	0	+2	dB	ATT=-1dB to -15dB
	Attenuation Set Error 2	Gv_err2	-3	0	+3	dB	ATT=-16dB to -47dB
	Attenuation Set Error 3	Gv_err3	-4	0	+4	dB	ATT=-48dB to -79dB
	Output Impedance	Rout	-	-	50	Ω	V _{IN} =100mVrms
	Maximum Output Voltage	V _{OM}	2	2.35	-	Vrms	THD+N=1% BW=400Hz-30kHz

VP-9690A (Average value detection, effective value display) filter by Matsushita Communication is used for * measurement. Phase between input / output is same.

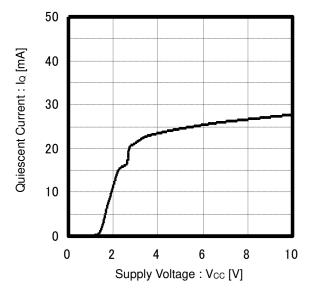


Figure 1. Quiescent Current vs Supply Voltage

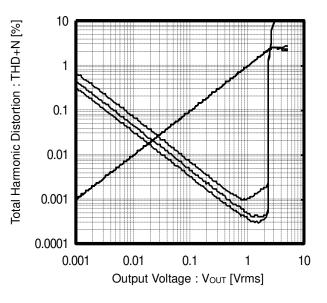


Figure 2. Total Harmonic Distortion vs Output Voltage

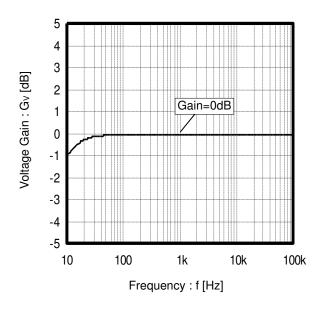


Figure 3. Voltage Gain vs Frequency

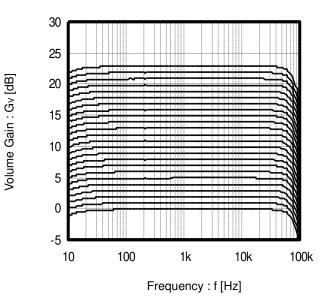
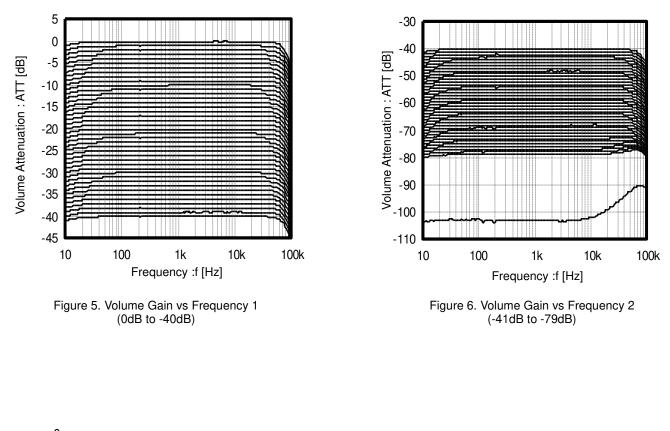


Figure 4. Volume Gain vs Frequency (0dB to +23dB)

Typical Performance Curves – continued



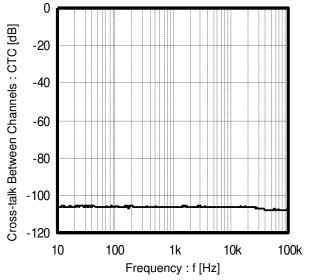


Figure 7. Cross-Talk Between Channels vs Frequency

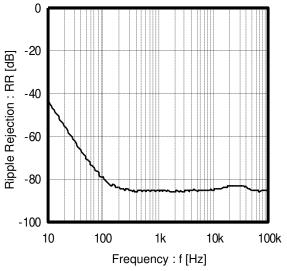
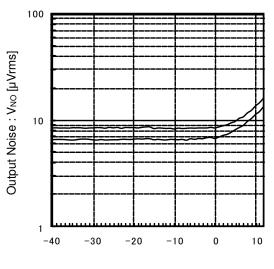


Figure 8. Ripple Rejection Ratio vs Frequency

Typical Performance Curves – continued



Volume Attenuation : ATT [dB]

Figure 9. Output Noise vs Volume Attenuation

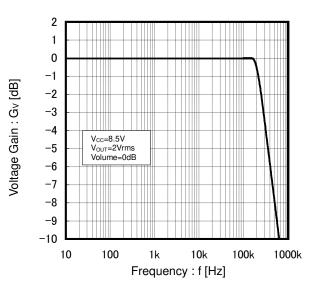


Figure 10. Volume Gain of Large Output Level vs Frequency

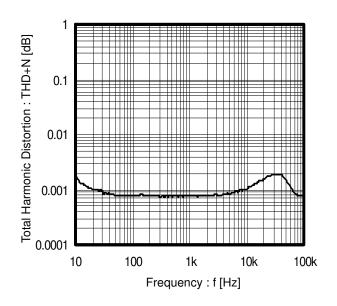


Figure 11. Total Harmonic Distortion vs Frequency

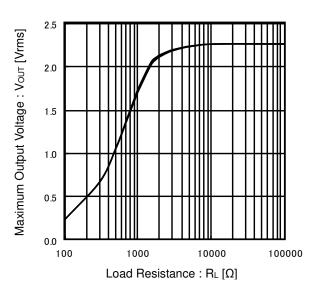


Figure 12. Maximum Output Voltage vs Load Resistance

Typical Performance Curves – continued

DC T		Sms/div (Sms/div) NORM290KS/s
• OU	FT	Million
4	a state of the sta	
	11.20mi 19.295/Wz	
OU	F2	MARINA MARINA
	. WITH BILL	

Figure 13. Advanced Switch 1

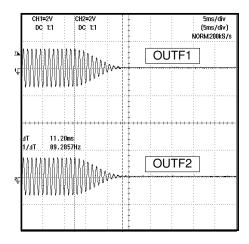


Figure 14. Advanced Switch 2

Timing Chart Control Signal Specifications

(1) Electrical Specifications and Timing for Bus Lines and I/O Stages

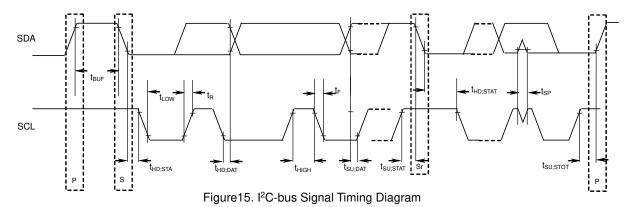


Table 1 Characteristics of the SDA and SCL bus lines for I²C-bus devices (Unless specified, Ta=25°C, Vcc=8.5V)

	Parameter	Cumbal	Fast-mod	Unit		
	Parameter	Symbol	Min	Max	Unit	
1	SCL clock frequency	fscl	0	400	kHz	
2	Bus free time between a STOP and START condition	t _{BUF}	1.3	-	μS	
3	Hold time (repeated) START condition. After this period, the first clock	+	0.6			
3	pulse is generated	thd;sta	0.6	-	μS	
4	LOW period of the SCL clock	t∟ow	1.3	-	μS	
5	HIGH period of the SCL clock	thigh	0.6	-	μS	
6	Set-up time for a repeated START condition	t _{su;sta}	0.6	-	μS	
7	Data hold time	thd;dat	0 (Note)	-	μS	
8	Data set-up time	tsu;dat	100	-	ns	
9	Set-up time for STOP condition	tsu;sto	0.6	-	μS	

All values referred to VIH Min and VIL Max Levels (see Table 2). (Note) To avoid sending right after the fall-edge of SCL (VIH min of the SCL signal), the transmitter sets a holding time of 300ns or more for the SDA signal. About 7(t_{HD:DAT}), 8(t_{SU:DAT}), make it the setup which a margin is fully in .

Table 2 Characteristics of the SDA and SCL I/O stages for I²C-bus devices

	Deremeter	Cumbal	Fast-mod	Unit	
	Parameter	Symbol	Min	Max	Unit
10	LOW level input voltage	VIL	-0.5	+1	V
11	HIGH level input voltage	Vін	2.3	-	V
12	Pulse width of spikes which must be suppressed by the input filter.	t _{SP}	0	50	ns
13	LOW level output voltage (open drain or open collector) at 3mA sink current	V _{OL1}	0	0.4	V
14	Input current of each I/O pin with an input voltage between 0.4V and 4.5V	h	-10	+10	uА

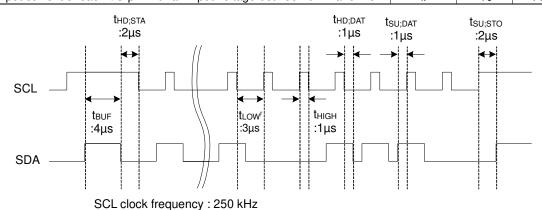


Figure 16. I²C Command Data Transmission Timing Diagram

(2) <u>I²C BUS FORMAT</u>

MSB	LSB	MSB L		LSB I		LSB						
S Slave Ad	ldress A	A Select Address		Α		Data	Α	Р				
1bit 8bit		-	bit	1bit		8bit	1bit	1bit				
S	= S	 Start condition (Recognition of start bit) 										
Slave A	Address = R	= Recognition of slave address. The first 7 bits correspond to the slave address.										
	TI	The least significant bit is "L" which corresponds to write mode.										
А	= A	= ACKNOWLEDGE bit (Recognition of acknowledgement)										
Select /	Address = S											
Data	= D	= Data on every volume and tone.										
Р	= S [.]	= Stop condition (Recognition of stop bit)										

(3) <u>I²C BUS Interface Protocol</u>

(a)	Basic forn	nat							
S	Slave A	ddress	Α	Select	Address	Α	Data	Α	Ρ
Ν	/ISB	LSB	Ν	ISB	LSB	MSI	B LSB		

(b) Automatic increment (Select Address increases (11) according to the number	
(b) Automatic increment (Select Address increases (+1) according to the number (b) according to the number of t	ber of data.

S	Slave Ad	dress	А	Select A	ddress	А	Dat	a1	А	Data2	А	 DataN	А	Р
N	ISB	LSB	Μ	SB	LSB	Μ	SB	LSB		MSB	LSB	MSB	LS	В

(Example) ①Data1 shall be set as data of address specified by Select Address.

②Data2 shall be set as data of address specified by Select Address +1.
 ③DataN shall be set as data of address specified by Select Address +N-1.

(c) Configuration unavailable for transmission (In this case, only Select Address1 is set.

<u>\-/</u>	<u> </u>					,					
S	Slave Address	Α	Select Address1	Α	Data	А	Select Address 2	Α	Data	Α	Ρ
MS	SB LSB	Μ	SB LSB	MS	SB LSB	M	SB LSB	MS	SB LSB		
(Note) If any data is transmitted as Select Address 2 next to data, it is recognized											
	as data, not as Select Address 2.										

(4) Slave Address

Because the slave address can be changed by the setting of CS, it is possible to use two chips at the same time on identical BUS.

	MSB							LSB	_
SEL Voltage Condition	A6	A5	A4	A3	A2	A1	A0	R/W	
GND to 0.2 x V _{CC}	1	0	0	0	0	0	0	0	80H 84H
0.8 x Vcc to Vcc	1	0	0	0	0	1	0	0	0411

Establish the CS voltage to define the setting.

Advanced Switch

(5) Select Address & Data

Items to be set	Select Address	MSB			Da	ata			LSB
items to be set	(hex)	D7	D6	D5	D4	D3	D2	D1	D0
Initial Setup 1	01	0	0	0	0	0	0	0	0
Volume 1ch Front	28	Volume Gain / Attenuation							
Volume 2ch Front	29	Volume Gain / Attenuation							
Volume 1ch Rear	2A	Volume Gain / Attenuation							
Volume 2ch Rear	2B			Vc	lume Gain	/ Attenuati	on		
Test Mode1	2C	1	1	1	1	1	1	1	1
Test Mode2	2D	1	1	1	1	1	1	1	1
Test Mode3	F0	0	0	0	0	0	0	0	0
System Reset	FE	1	0	0	0	0	0	0	1

(Note) 1. The Advanced Switch works in the latch part while changing from one function to another.

2. Upon continuous data transfer, the Select Address rolls over because of the automatic increment function, as shown below.

$$\rightarrow 01 \rightarrow 28 \rightarrow 29 \rightarrow 2A \rightarrow 2B \rightarrow 2C \rightarrow 2D$$

Select address 28, 29, 2A, 2B(hex)

Gain & ATT	MSB		Volum	e Gair	n/Atten	uation		LSB
Gain & ATT	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
— (Nata)	0	0	0	0	0	0	0	1
Prohibition (Note)	:	•••	:	:	:	•••	:	:
	0	1	1	0	1	0	0	0
23dB	0	1	1	0	1	0	0	1
22dB	0	1	1	0	1	0	1	0
21dB	0	1	1	0	1	0	1	1
:	:	:	:	:	:		:	:
-78dB	1	1	0	0	1	1	1	0
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition (Note)		•	:	:	:		:	:
	1	1	1	1	1	1	1	0
-∞dB	1	1	1	1	1	1	1	1

(Note) Gain is set to "-∞dB" when sending "Prohibition data".

(6) About Power ON Reset

Initialization inside IC is carried out at one of supply voltage circuits. Initial data is sent to all addresses at supply voltage ON. Mute is ON until this initial data is sent.

Deremeter	Cumbol		Limit		Linit	Conditions	
Parameter	Symbol	Min	Тур	Max	Unit		
Rise Time of VCC	trise	20	-	-	µsec	V_{CC} rise time from 0V to 3V	
VCC Voltage of Release Power ON Reset	V _{POR}	-	4.1	-	V		

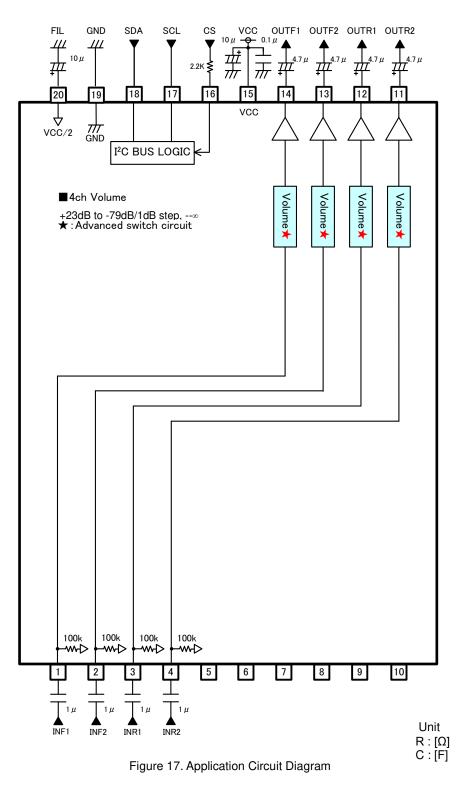
Application Information

1. Volume Gain/Attenuation of the details

	ume			uation														
(dB)	D7	D6	D5	D4	D3	D2	D1	D0		(dB)	D7	D6	D5	D4	D3	D2	D1	D0
+23	0	1	1	0	1	0	0	1		-29	1	0	0	1	1	1	0	1
+22	0	1	1	0	1	0	1	0		-30	1	0	0	1	1	1	1	0
+21	0	1	1	0	1	0	1	1		-31	1	0	0	1	1	1	1	1
+20	0	1	1	0	1	1	0	0		-32	1	0	1	0	0	0	0	0
+19	0	1	1	0	1	1	0	1		-33	1	0	1	0	0	0	0	1
+18	0	1	1	0	1	1	1	0		-34	1	0	1	0	0	0	1	0
+17	0	1	1	0	1	1	1	1		-35	1	0	1	0	0	0	1	1
+16	0	1	1	1	0	0	0	0		-36	1	0	1	0	0	1	0	0
+15	0	1	1	1	0	0	0	1		-37	1	0	1	0	0	1	0	1
+14	0	1	1	1	0	0	1	0		-38	1	0	1	0	0	1	1	0
+13	0	1	1	1	0	0	1	1		-39	1	0	1	0	0	1	1	1
+12	0	1	1	1	0	1	0	0		-40	1	0	1	0	1	0	0	0
+11	0	1	1	1	0	1	0	1	Γ	-41	1	0	1	0	1	0	0	1
+10	0	1	1	1	0	1	1	0	Γ	-42	1	0	1	0	1	0	1	0
+9	0	1	1	1	0	1	1	1	Γ	-43	1	0	1	0	1	0	1	1
+8	0	1	1	1	1	0	0	0		-44	1	0	1	0	1	1	0	0
+7	0	1	1	1	1	0	0	1		-45	1	0	1	0	1	1	0	1
+6	0	1	1	1	1	0	1	0		-46	1	0	1	0	1	1	1	0
+5	0	1	1	1	1	0	1	1	Ē	-47	1	0	1	0	1	1	1	1
+4	0	1	1	1	1	1	0	0	Ē	-48	1	0	1	1	0	0	0	0
+3	0	1	1	1	1	1	0	1	Ē	-49	1	0	1	1	0	0	0	1
+2	0	1	1	1	1	1	1	0	Ē	-50	1	0	1	1	0	0	1	0
+1	0	1	1	1	1	1	1	1		-51	1	0	1	1	0	0	1	1
0	1	0	0	0	0	0	0	0	-	-52	1	0	1	1	0	1	0	0
-1	1	0	0	0	0	0	0	1		-53	1	0	1	1	0	1	0	1
-2	1	0	0	0	0	0	1	0	-	-54	1	0	1	1	0	1	1	0
-3	1	0	0	0	0	0	1	1	-	-55	1	0	1	1	0	1	1	1
-4	1	0	0	0	0	1	0	0	-	-56	1	0	1	1	1	0	0	0
-5	1	0	0	0	0	1	0	1	-	-57	1	0	1	1	1	0	0	1
-6	1	0	0	0	0	1	1	0	-	-58	1	0	1	1	1	0	1	0
-7	1	0	0	0	0	1	1	1	-	-59	1	0	1	1	1	0	1	1
-8	1	0	0	0	1	0	0	0	-	-60	1	0	1	1	1	1	0	0
-9	1	0	0	0	1	0	0	1	-	-61	1	0	1	1	1	1	0	1
-10	1	0	0	0	1	0	1	0	-	-62	1	0	1	1	1	1	1	0
-11	1	0	0	0	1	0	1	1	-	-63	1	0	1	1	1	1	1	1
-12	1	0	0	0	1	1	0	0	-	-64	1	1	0	0	0	0	0	0
-12	1	0	0	0	1	1	0	1		-65	1	1	0	0	0	0	0	1
-14	1	0	0	0	1	1	1	0		-66	1	1	0	0	0	0	1	0
-14	1	0	0	0	1	1	1	1		-67	1	1	0	0	0	0	1	1
-15	1	0	0	1	0	0	0	0		-68	1	1	0	0	0	1	0	0
-10	1	0	0	1	0	0	0	1		-69	1	1	0	0	0	1	0	1
-17	1	0	0	1	0	0	1	0		-09	1	1	0	0	0	1	1	0
-18	1	0	0	1	0	0	1	1		-70	1	1	0	0	0	1	1	1
-19 -20	1	0	0	1	0	1	0	0		-71	1	1	0	0	1	0	0	0
-20	1	0	0	1	0	1	0	1		-72	1	1	0	0	1	0	0	1
-21	1	0	0	1	0	1	1	0		-73	1	1	0	0	1	0	1	0
	1	0	0	1	0	1	1	1	-	-74	1	1	0	0	1	0	1	1
-23			-											-				
-24	1	0	0	1	1	0	0	0		-76	1	1	0	0	1	1	0	0
-25	1	0	0		1	0	0	1		-77	1	1	0	0	1	1	0	1
-26	1	0	0	1	1	0	1	0		-78	1	1	0	0	1	1	1	0
-27	1	0	0	1	1	0	1	1		-79	1	1	0	0	1	1	1	1
-28	1	0	0	1	1	1	0	0		- 00	1	1	1	1	1	1	1	1

: Initial condition

2. Application Circuit Diagram



Notes on wiring

- ① Please connect the decoupling capacitor of the power supply in the shortest distance as much as possible to GND.
- 2 Lines of GND shall be one-point connected.
- ③ Wiring pattern of Digital shall be away from that of analog unit and cross-talk shall not be acceptable.
 ④ Lines of SCL and SDA of I²C BUS shall not be parallel if possible.
- The lines shall be shielded, if they are adjacent to each other.
- (5) Lines of analog input shall not be parallel if possible. The lines shall be shielded, if they are adjacent to each other.

Power Dissipation

About the thermal design by the IC

Characteristics of an IC have a great deal to do with the temperature at which it is used, and exceeding absolute maximum ratings may degrade and destroy elements. Careful consideration must be given to the heat of the IC from the two standpoints of immediate damage and long-term reliability of operation.

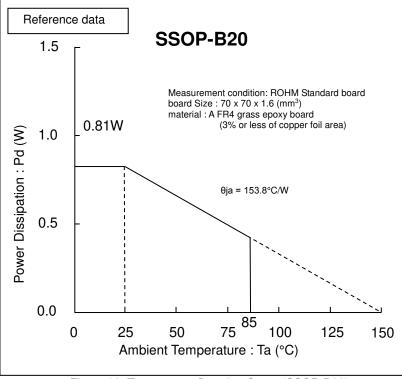


Figure 18. Temperature Derating Curve (SSOP-B20)

Power dissipation values vary according to the board on which the IC is mounted.

⁽Note) Values are actual measurements and are not guaranteed.

I/O Equivalent Circuits

Terminal No.	Terminal Voltage	Equivalent Circuit	Terminal Description
INF1 INF2 INR1 INR2	4.25		Signal input terminal. The input impedance is 100kΩ(typ).
OUTR2 OUTR1 OUTF2 OUTF1	4.25	VCC GND	Fader output terminal.
CS	-	VCC T GND GND	Slave address selection terminal. "CS" is "High" to slave address "84 H" "CS" is "Low" to slave address "80 H"

The values in the input/output equivalent circuits are reference values only and are not guaranteed.

I/O Equivalent Circuits – continued

Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
VCC	8.5		Power supply terminal.
SCL	-	VCC VCC I.65V GND	Clock input terminal of I ² C BUS communication.
SDA	-	VCC VCC VCC VCC VCC VCC VCC VCC	Data input terminal of I ² C BUS communication.
GND	0		Ground terminal.
FIL	4.25		Voltage terminal for reference bias of analog signal system. The simple precharge circuit and simple discharge circuit for an external capacitor are built in.

The values in the input/output equivalent circuits are reference values only and are not guaranteed.

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

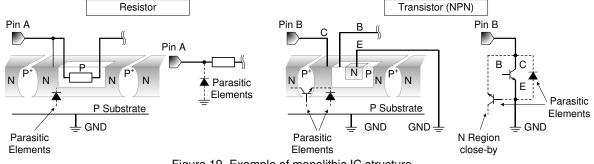
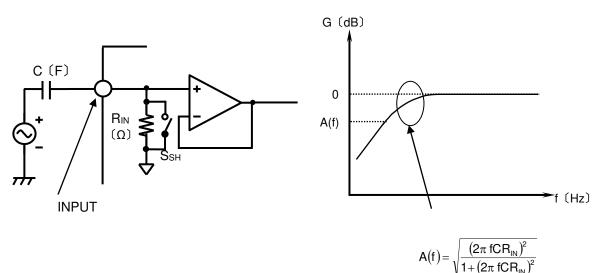


Figure 19. Example of monolithic IC structure

13. About a Signal Input Part

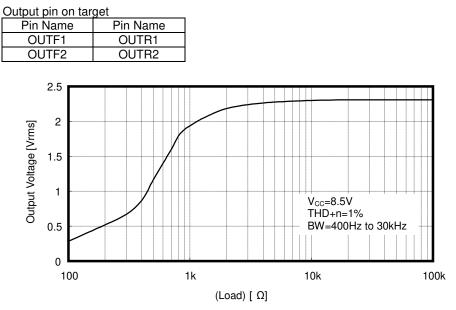
About Input Coupling Capacitor Constant Value

The constant value of input coupling capacitor C(F) is decided with respect to the input impedance $R_{IN}(\Omega)$ at the input signal terminal of the IC. The first HPF characteristic of RC is composed.



14. About Output Load Characteristics

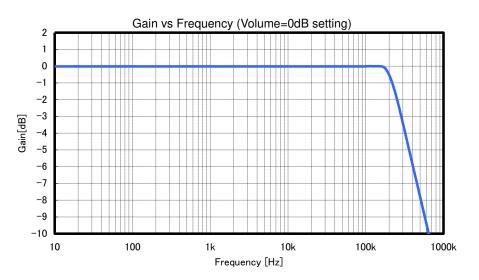
The usages of output load are below (reference). Please use more than $10[k\Omega]$ (TYP) load.



Output Load Characteristic at V_{CC}=8.5V. (Reference)

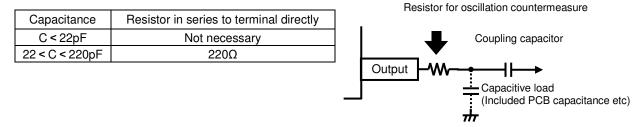
15. Frequency Characteristic at Large Output Level

High slew-rate amplifiers are used for high quality sound. This IC corresponds to "192kHz sampling on DVD-Audio" which is highest quality. Output level is "2Vrms, 192kHz flat(typ)". (See the below graph (reference)).



16. Oscillation Countermeasure for Volume Outputs at Power Supply ON/OFF

Using higher capacitance than 22pF at volume outputs may cause oscillation at the moment you turn ON/OFF the power supply (when V_{CC} is about 3V to 4V). As oscillation countermeasure, insert resistor in series to terminal directly as shown below, and set volume output to mute outside this device when turning ON/OFF the power supply.



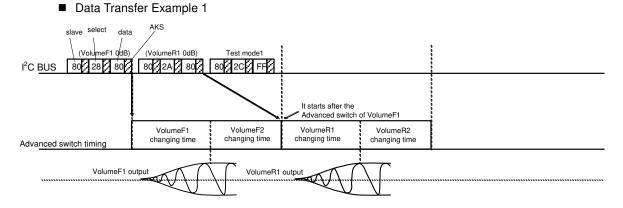
17. I²C BUS Transferring Data

[1] Types of Data Transfer

- 1-1. The data transfer without Advanced Switch (data transfer without data latching format) does not have regulations on transferring data.
- 1-2. The data transfer with Advanced Switch (data transfer with data latching format) does not have regulations on transferring data too. But Advanced Switch data transfer follows the order in [2].

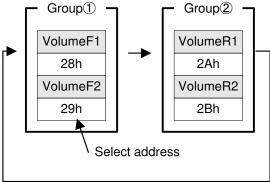
[2] Advanced Switch Data Transfer

2-1. The timing chart of Advanced Switch data transfer is as follows.



(Note) It is the same even if it transfers data in auto increment mode.

There are no timing regulations in I²C BUS transferring data. But the changing time starts after the end of the present change. In addition, the timing of Advanced Switch is not dependent on transferring data turn. Instead, it follows the following turn.

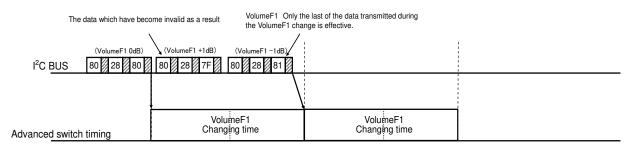


Advanced Switch Start Turn

(Note) The block in the same group can start the Advanced Switch at the same time.

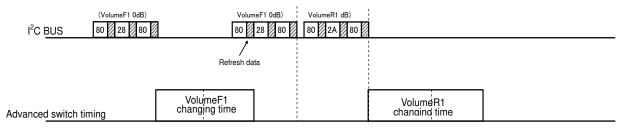
Data Transfer Example 2

Priority is given to the data of the same select address when it is transferred to the timing which Advanced Switch has not ended. In addition, when two or more data are transferred to the same select address, the end transferred data is effective.



Data Transfer Example 3 Refresh data is the same as the present setup data, therefore Advanced switch does not change.

The gain change data of other channels are transferred after refresh data as below.

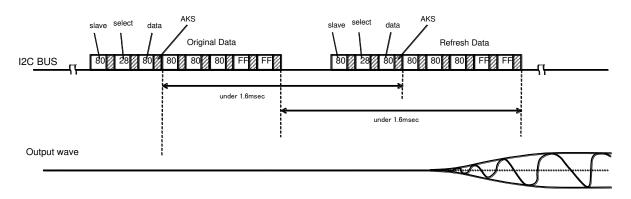


[3] Attention on Transferring Data

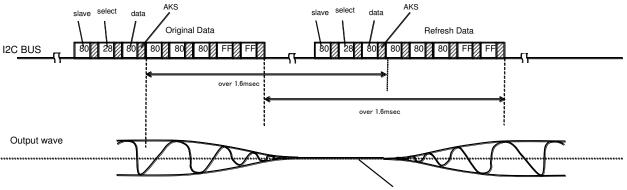
- BD3464FV cannot set the data transfer from a microcomputer correctly on very rare occasions. In such cases, the following phenomenon may occur.
 - 1. Volume gain does not change.
 - 2. Volume gain changes to MUTE.

Therefore, the data transfer from a microcomputer should send data as shown in the following conditions.

① When sending the Volume change data, please send the same data twice as below.

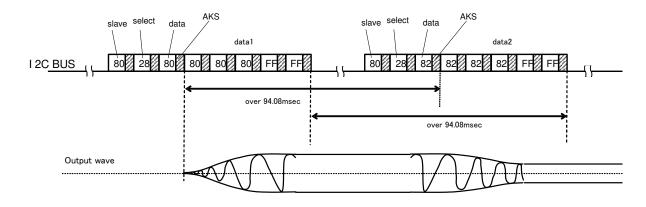


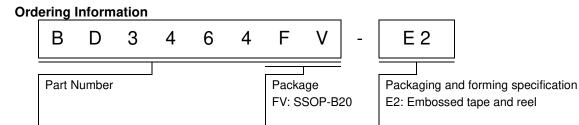
If Refresh data can't be sent like ①timing, the output wave may be put on mute momentarily.



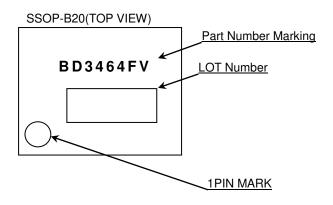
Output wave may not change the gain or may be mute until refresh data reception.

② If Volume change data can send over 94.08msec interval transferring data, there is no need to send Refresh data.

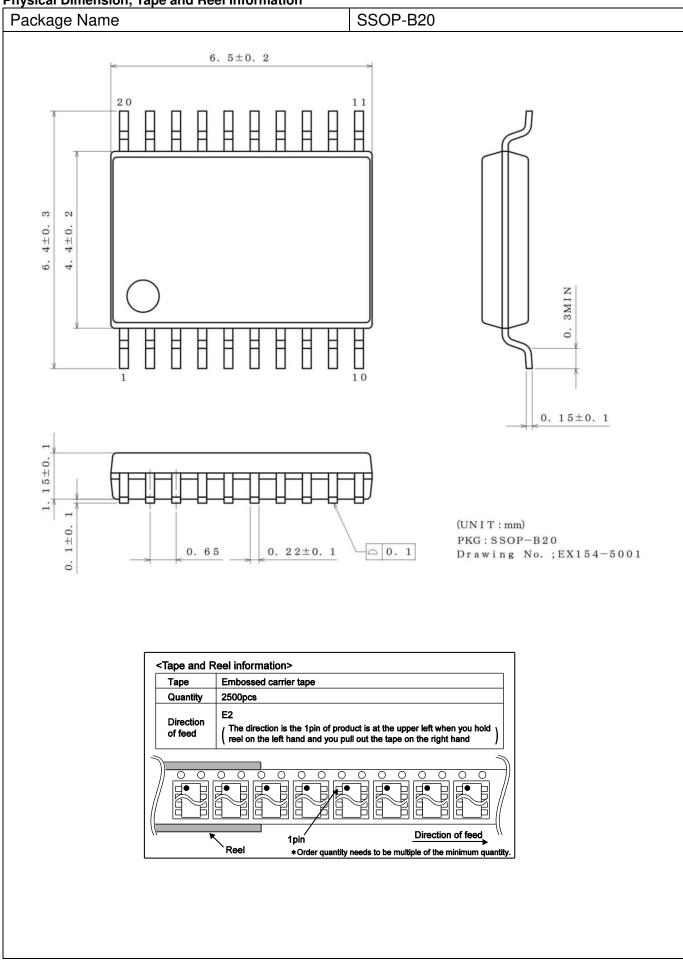




Marking Diagram



Physical Dimension, Tape and Reel Information



Revision History

Date	Revision	Changes
16.Dec.2015	001	New Release

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CLASSⅢ	CLASSⅢ	CLASS II b			
CLASSⅣ	CLASSIII	CLASSⅢ	CLASSII		

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